

**WAFER BONDING: APPLICATIONS AND TECHNOLOGY
(SPRINGER SERIES IN MATERIALS SCIENCE)**

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Table 1 summarizes some of the representative demonstrations
of hybrid silicon lasers through wafer bonding technology.
Injection current is mA and the corresponding voltage is 4 V.
Considering the complete integration with existing silicon photonic integ
Springer, Park, Soo-Jin Such thick silicon layer does not
match with the current mainstream silicon photonics.
Furthermore, due to the weak interaction between the optical mode and gain ma
Kolja Kolata, Ryan B.